


- 1 Substrate: 3.18mm  $\pm$ 0.025mm [0.125"  $\pm$ 0.001"] FR4/G10 or equivalent high temp material. 17 $\mu$ m [1/2 oz.] Cu clad. SnPb plating.
- 2 Solder ball: Eutectic Sn63Pb37

Description: BGA Surface Mount Adaptor  
 256 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	<b>SF-BGA256E-B-05 Drawing</b> © 2002 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Status: Released	Scale: 3:1	Rev: B
		Drawing: H. Hansen File: SF-BGA256E-B-05 Dwg		Date: 8/14/02 Modified: 4/12/05